# **AN8014S**

### Step-down, step-up, or inverting DC-DC converter control IC

#### Overview

The AN8014S is a single-channel PWM DC-DC converter control IC.

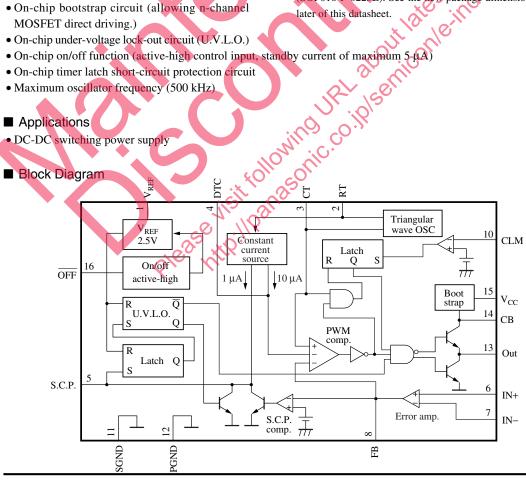
This IC can provide any one output type from among step-down, step-up and inverting output.

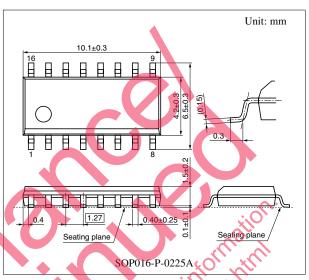
Allowing n-channel power MOSFET direct driving, the AN8014S is ideal for high-efficiency power supplies.

#### Features

- Wide operating supply voltage range (3.6 V to 34 V) (The voltage is limited within a range between 3.6 V and 17 V if it is connected to a step-down voltage circuit.)
- Totem pole output circuit: output peak current (±1 A)
- On-chip pulse-by-pulse overcurrent detection and protection circuit
  - Threshold voltage  $V_{CC} 0.095$  V typical
- On-chip bootstrap circuit (allowing n-channel







Note) The package of this product will be changed to lead-free type (SOP016-P-0225E). See the new package dimensions section later of this datasheet.

#### Pin Descriptions

Pin No.	Description	Pin No.	Description
1	Internal reference output	9	Not connected
2	Oscillator timing resistor connection	10	Overcurrent protection input
3	Oscillator timing capacitor connection	11	Signal ground
4	Dead-time control	12	Output stage ground
5	Capacitance connection for short-circuit	13	Totem pole type output
	protection delay	14	Bootstrap output
6	Error amplifier noninverting input	15	Supply voltage
7	Error amplifier inverting input	16	On/off control
8	Error amplifier output		

#### ■ Absolute Maximum Ratings

8	Error amplifier output			
■ Absolute	e Maximum Ratings		<u>~`.()</u>	- C ·
	Parameter	Symbol	Rating	Unit
Supply vol	tage	Vcc	35	n'o X
Supply cur	rent	I <sub>CC</sub>	¥0	mA
Power diss	ipation *2	P <sub>D</sub>	143	+ mW
Operating	ambient temperature *1	T <sub>opr</sub>	-30 to +85	°C
Storage ter	nperature *1	T <sub>stg</sub>	-40 to +125	°C
On/off pin	allowable application voltage	V <sub>ON/OFF</sub>	Valuation	V
Error ampl	ifier allowable input voltage	VI	- 0,3 to V <sub>REF</sub>	V
DTC pin a	llowable application voltage	V <sub>DTC</sub>	$-0.3$ to $V_{REF}$	V
Out pin all	owable application voltage	V <sub>OUT</sub>	35	V
Out pin con	nstant output current	I <sub>0</sub>	±100	mA
Out pin pe	ak output current	I <sub>O(Peak)</sub>	±1000	mA
CB pin allo	owable application voltage	VCBO	35	V
CB pin cor	nstant output current	ССВ	-100, 150	mA
CB pin pea	ak output current	ICBE	-500, 1 000	mA
CLM pin a	llowable application voltage	Vеlм	V <sub>CC</sub>	V

Note) 1. \*1: Except for the operating ambient temperature and storage temperature, all ratings are for  $T_a = 25^{\circ}C$ . \*2: At  $T_a = 85^{\circ}C$ 

2. Do not apply external currents or voltages to any pins not specifically mentioned. For circuit currents, '+' denotes current flowing into the IC, and '-' denotes current flowing out of the IC.

#### Recommended Operating Range

Parameter	Symbol	Rang	e	Unit
Supply voltage	V <sub>CC</sub>	Step-up circuit system	3.6 to 34	V
		Step-down circuit system	3.6 to 17	

#### ■ Electrical Characteristics at V<sub>CC</sub> = 12 V, T<sub>a</sub> = 25°C

Parameter	Symbol	Conditions	Min	Тур	Max	Uni
Reference voltage block						
Output voltage	V <sub>REF</sub>	$I_{REF} = -1 \text{ mA}$	2.522	2.6	2.678	V
Line regulation with input fluctuation	Line	$V_{CC} = 3.6 \text{ V} \text{ to } 34 \text{ V}$		16	25	m۷
Load regulation	Load	$I_{REF} = -0.1 \text{ mA to } -1 \text{ mA}$	-	1	10	m
U.V.L.O. block						
Circuit operation start voltage	V <sub>UON</sub>	-	2.8	3.1	3.4	V
Hysteresis width	V <sub>HYS</sub>	-	60	140	180	m
Error amplifier block						
Input offset voltage	V <sub>IO</sub>		-6		6	m
Input bias current	I <sub>B</sub>		-500	-25		nA
Common-mode input voltage range	V <sub>ICR</sub>		-0.1		0.8	v
High-level output voltage	$V_{\rm EH}$		V <sub>REF</sub>	V <sub>REF</sub>	<del>, </del>	v
			- 0.3	- 0.1	Q.,	
Low-level output voltage	V <sub>EL</sub>		—	0.1	0.3	V
Dead-time control circuit block					i, r	
Input current	I <sub>DTC</sub>		-15.8	-132	-10.6	μ
Low-level input threshold voltage	V <sub>DT-L</sub>	Duty 0%		0.45	0.65	V
High-level input threshold voltage	V <sub>DT-H</sub>	Duty 100%	1.2	1.4	—	V
Output block			<u>,                                    </u>			
Oscillator frequency	f <sub>OUT</sub>	$C_{\rm T} = 120 \text{ pF}, R_{\rm T} = 15 \text{ k}\Omega$	196	218	240	kH
Output duty	Du	$R_{\rm DTC} = 75 \ \rm k\Omega$	47	52	57	%
Low-level output voltage	V <sub>OL</sub>	$I_0 = 70 \text{ mA}$		1.0	1.3	V
High-level output voltage	V <sub>OH</sub>	$I_0 = -70 \text{ mA}$	V <sub>CB</sub>	V <sub>CB</sub>		V
		10° allo	-2.0	-1.0		
Bootstrap circuit block	,	the go	1			
Input standby voltage	V <sub>INCB</sub> C	$I_{CB} = -70 \text{ mA}$	V <sub>CC</sub> -1.2	V <sub>CC</sub>	V <sub>CC</sub>	V
Short airquit protection airquit bla		112	-1.2	-1.0	- 0.8	
Short-circuit protection circuit blo	$\sim \times \times$	)* <sup>*</sup>	0.70	0.75	0.00	τ,
Input threshold voltage	VTHPC		0.70	0.75	0.80	V
Input standby voltage	V <sub>STBY</sub>			30	120	m
Input latch voltage	V <sub>IN</sub>			30	120	m
Charge current	I <sub>CHG</sub>		-2.76	-2.30	-1.84	μA
On/off control block						
Threshold voltage	V <sub>TH</sub>	—	0.8		2.0	V
Overcurrent protection block			1			
Threshold voltage	V <sub>CLM</sub>	—	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V

### Electrical Characteristics at $V_{CC} = 12 \text{ V}$ , $T_a = 25^{\circ}C$ (continued)

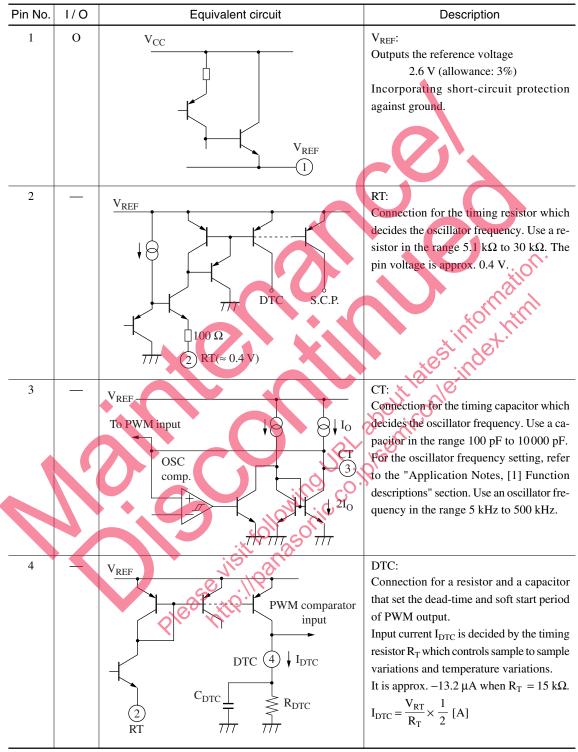
Parameter	Symbol	mbol Conditions		Тур	Max	Unit
Whole device						
Total consumption current	I <sub>CC</sub>			5.0	7.0	mA
Standby current	I <sub>CC(SB)</sub>			_	5	μA

#### • Design reference data

Note) The characteristics listed below are theoretical values based on the IC design and are not guaranteed.

Parameter	Symbol	Conditions	Limit	Unit			
Reference voltage block							
Output voltage temperature characteristics 1	V <sub>TC1</sub>	$T_a = -30^{\circ}C$ to $+25^{\circ}C$	±1	%			
Output voltage temperature characteristics 2	V <sub>TC2</sub>	$T_a = 25^{\circ}C \text{ to } 85^{\circ}C$	±1	%			
Output short-circuit current	I <sub>OS</sub>		-40 0	mA			
Error amplifier block			a na a				
Output sink current	I <sub>SINK</sub>	$V_{\rm FB} = 0.9 \ V$	481 tr	mA			
Output source current	I <sub>SOURCE</sub>	$V_{FB} = 0.9 V$	-110-	μΑ			
Open-loop gain	A <sub>G</sub>		× CS , TO	dB			
Output block			2				
Frequency supply voltage characteristics	f <sub>dV</sub>	$f_{OUT} = 200 \text{ kHz},$ $V_{CC} = 3.6 \text{ V to } 34 \text{ V}$	jonie ±3	%			
Frequency temperature characteristics 1	f <sub>dT1</sub>	$f_{OUT} = 200 \text{ kHz},$ $T_a = -30^{\circ}\text{C to} +25^{\circ}\text{C}$	±9	%			
Frequency temperature characteristics 2	f <sub>dT2</sub>	$f_{OUT} = 200 \text{ kHz},$ $T_a = 25^{\circ}\text{C}$ to $85^{\circ}\text{C}$	±9	%			
Oscillator block	7	10th dic.					
RT pin voltage	V <sub>RT</sub>	40 <sup>11</sup> 60 <sup>1</sup> -	0.4	V			
Short-circuit protection circuit bl	•	an and					
Comparator threshold voltage	VTHL	110° -	1.87	V			
Overcurrent protection circuit blo	ock xC						
Delay time	t <sub>DLY</sub>	—	200	ns			

#### Terminal Equivalent Circuits



Terminal Equivalent Circuits (continued)

Pin No.	1/0	Equivalent circuit	Description
5		V <sub>REF</sub> $I_{CHG}$ U.V.L.O. utput TT 5 S.C.P. TT	S.C.P.: Connection for the capacitor that sets the soft start period and the timer latch short- circuit protection circuit time constant. Use a capacitor with a value of 1 000 pF or higher. The charge current I <sub>CHG</sub> is decided by the timing resistor R <sub>T</sub> which controls sample to sample variations and temperature varia- tions. It is approx2.3 $\mu$ A when R <sub>T</sub> = 15 k $\Omega$ . I <sub>CHG</sub> = $\frac{V_{RT}}{R_T} \times \frac{1}{11}$ [A].
6	Ι	V <sub>REF</sub>	IN+: Noninverting input to the error amplifier. Use the common-mode input in the range -0.1 V to +0.8 V.
7	Ι		IN-: Inverting input to the error amplifier. Use the common-mode input in the range - 0.1 V to +0.8 V.
8	Ο	VREF Source current 8 FB VIII Sink current	FB: Output from the error amplifier. The source current is approx. $-110 \mu\text{A}$ and sink current is approx. 8 mA. Correct the frequency characteristics of the gain and the phase by connecting a re- sistor and a capacitor between this pir and IN- pin.
9 10	I	V <sub>cc</sub> 0.1 V 50 μA	N.C.: Not connected. CLM: Detects the overcurrent state in switching transistor. Insert a resistor with a low resistance between this pin and $V_{CC}$ to detect overcurrent states. When this pin falls to a level 95 mV or more lower than $V_{CC}$ , the PWM output is turned off for that period thus narrowing the width of the on-period. (This implements a pulse-by-pulse overcurrent protection technique.)

Pin No.	I/O	Equivalent circuit	Description
11	_	(11) SGND	SGND: Signal ground.
12		(12) GND	GND: Output stage ground.
13	Ο		Out: Totem pole output. A constant output current of ±100 mA or peak output current of ±1 A can be o tained.
14	0	TTT (3) Our	CB: Bootstrap output. Connect a bootstrap capacitor betwee this pin and the n-channel MOSFET source side pin of the switching element who using a step-down voltage circuit. Short-circuit this pin and the V <sub>CC</sub> pin who using a step-up voltage circuit.
15	Ι		Vcc: Powersupply.
16	I	$ \begin{array}{c}                                     $	$\overline{OFF}$ :Controls the on/off state.When the input is high: normal operation $(V_{\overline{OFF}} > 2.0 \text{ V})$ When the input is low: standby mode $(V_{\overline{OFF}} < 0.8 \text{ V})$ In standby mode, the total current constmption is held to under 10 $\mu$ A.

Terminal Equivalent Circuits (continued)

#### Application Notes

- [1] Function descriptions
  - 1. Reference voltage block

This block is composed of the band gap circuit and outputs the temperature compensated reference voltage (2.6 V) to the  $V_{REF}$  pin (pin 1). The reference voltage is stabilized when the supply voltage is 3.6 V or more and used as the operating power supply in IC. It is possible to take out a load current of up to -1 mA.

- [1] Function descriptions (continued)
  - 2. The triangular wave generator block (OSC)

The triangular wave which swings from approximately 1.32 V (upper limit value,  $V_{OSCH}$ ) to approximately 0.44 V (lower limit value,  $V_{OSCL}$ ) will be generated by connecting a timing capacitor  $C_T$  and a resistor  $R_T$  to the  $C_T$  pin (pin 3) and  $R_T$  pin (pin 2) respectively. Oscillator frequency can be freely decided by the value of  $C_T$  and  $R_T$  connected externally. The oscillator frequency  $f_{OSC}$  is obtained by the following formula;

$$f_{OSC} = \frac{1}{t_1 + t_2} = \frac{I_0}{2 \times C_T \times (V_{CTH} - V_{CHL})}$$

$$I_0 = 1.7 \times \frac{V_{RT}}{R_T} = 1.7 \times \frac{0.4}{R_T}$$
Because  $V_{CTH} - V_{CTL} = 0.88 V$ 

$$f_{OSC} \approx \frac{1}{2.59 \times C_T \times R_T}$$
[Hz]
Example) An  $f_{OSC}$  of approximately 215 kHz will be obtained if  $C_T$  is 120 pF and  $R_T$  is 15 kΩ.
Figure 1. Triangular oscillation waveform

It is possible to use the circuit in the recommended operating range of 5 kHz to 500 kHz of the oscillator frequency. As the AN8014S is used at increasingly higher frequencies, the amount of overshoot and undershoot due to the operation delay in the triangular wave oscillator comparator increases, and discrepancies between the values calculated as described previously and the actual values may occur.

The output source currents of the AN8014S's S.C.P. and DTC pins are determined by the timing resistor  $R_T$  which is externally connected to the RT pin. Therefore, note that this IC can not be used as an IC for slave when the several ICs are operated in parallel synchronous mode.

3. Error amplifier block

Detecting and amplifying DC-DC converter output voltage, the error amplifier with pnp transistor input inputs the signal to the PWM comparator.

Figure 2 shows the way to connect the error amplifier.

The common-mode input voltage range is -0.1 V to +0.8 V, and a voltage obtained by dividing the reference voltage with built-in resistors is applied to the non-inverting input. Connecting the feedback resistor and the capacitor between the error amplifier output pin (pin 8) and the inverting input pin (pin 7) allows the arbitrary gain setting and the phase compensation.

Startup overshooting caused by feedback delays will be suppressed by setting the output source current and output sink current to as high as 110  $\mu$ A and 8 mA respectively.

The input voltage  $V_{IN+}$  and  $V_{IN-}$  to the error amplifier are obtained from the following formulas.

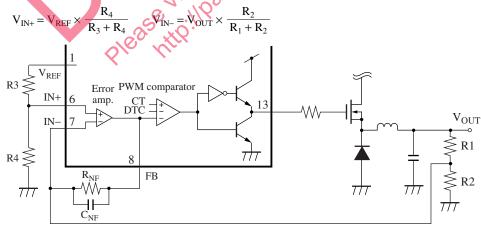


Figure 2. Connection method of error amplifier

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- [1] Function descriptions (continued)
- Timer latch short-circuit protection circuit

This circuit protects external main switching devices, flywheel diodes, choke coils and so forth from breakdown or deterioration when overload or short-circuit of power supply lasts a certain time.

Figure 3 shows the short-circuit protection circuit. The timer latch short-circuit protection circuit detects the output level of the error amplifier.

If the output voltage of the DC-DC converter is stable, the output of the error amplifier from the FB pin is stable and the short-circuit protection comparator is well balanced.

In that case, the transistor Q1 is conductive and the S.C.P. pin voltage is approximately 30 mV constantly.

If the load condition changes radically and output signal voltage of the error amplifier (FB) is 1.87 V or higher, the short-circuit protection comparator outputs low-level voltage. Then, by cutting off the transistor Q1, the external capacitor  $C_{S}$  of S.C.P. pin (pin 5) starts charging with the current I<sub>CHG</sub> which is obtained from the following formulas.

$$V_{PE} = V_{STBY} + I_{CHG} \times \frac{t_{PE}}{C_S} \quad [V]$$
  
0.75 V = 0.03 V + I<sub>CHG</sub> ×  $\frac{t_{PE}}{C_S}$   
 $C_S = I_{CHG} \times \frac{t_{PE}}{0.72} \quad [F]$ 

 $I_{CHG}$  is constant current which is determined by the timing resistor  $R_T$ . If  $R_T$  is 15 k $\Omega$ ,  $I_{CHG}$  will be approximately 2.3  $\mu$ A

$$I_{CHG} = \frac{V_{RT}}{R_T} \times \frac{1}{11}$$

est information When the external capacitor Cs is charged up to approximately 0.75 V, the latch circuit will be turned on. Then the totem-pole output pin will be set to low level and the dead-time will be set to 100%.

When the latch circuit is turned on, the S.C.P. pin will discharge electricity till the voltage on the S.C.P. pin reduces to approximately 30 mV. The latch circuit cannot be, however, reset until power supply to the AN8014S is turned off.

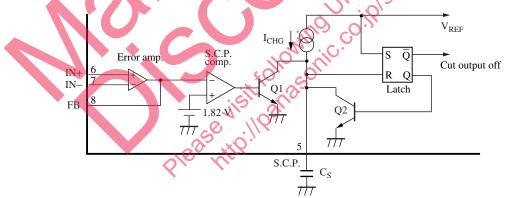


Figure 3. Short-circuit protection circuit

#### 5. Low input voltage malfunction prevention circuit (U.V.L.O.)

This circuit protects system from breakdown or deterioration caused by malfunction in control circuit when supply voltage is dropped during transient time at power on or off.

The low input voltage malfunction prevention circuit detects internal reference voltage which changes in accordance with the supply voltage level. When the supply voltage is turned on, it sets the dead-time of Out pin (pin 13) to 100% and keeps the DTC pin (pin 4) and S.C.P. pin (pin 5) low level until the supply voltage reaches 3.1 V. When the supply voltage falls, it will operate even below 2.96 V because of its hysteresis width of 140 mV.

#### [1] Function descriptions (continued)

6. Remote circuit

It is possible to switch on or off the IC control by using an external control signal. When the  $\overline{OFF}$  pin (pin 16) voltage is lowered to below approximately 0.8 V, the internal reference voltage goes down thereby stopping the IC control and reducing the circuit current to 5  $\mu$ A or less. When the  $\overline{OFF}$  pin voltage is increased to approximately 2.0 V or more, the internal reference voltage rises thereby starting the control operation.

7. PWM comparator block

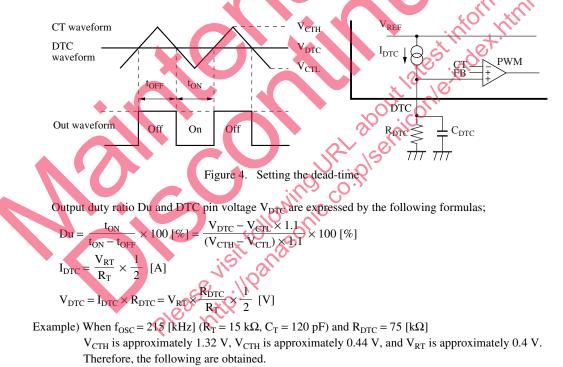
The PWM comparator controls the on-period of output pulse in accordance with the input voltage. While the triangular wave voltage on the CT pin (pin 3) is lower than both the error amplifier's output voltage on pin 8 and the voltage on the DTC pin (pin 4), the output on the Out pin (pin 13) will be set to high level. Then the switching element (n-channel MOSFET) will be turned on.

The dead-time is set by adjusting the voltage  $V_{DTC}$  on the DTC pin (pin 5) as shown in figure 4.

The DTC pin has constant current output determined by the resistor  $R_T$ . Therefore  $V_{DTC}$  is adjusted by connecting the DTC and GND pins through the external resistor  $R_{DTC}$ .

When the oscillator frequency  $f_{OSC}$  is 200 kHz, the output duty cycle will be 0% at  $V_{DTC}$  of 0.44 V typical and 100% at  $V_{DTC}$  of 1.32 V typical.

The levels of overshooting and undershooting of the peak value  $V_{\text{CTH}}$  and the trough value  $V_{\text{CTL}}$  of the triangular wave vary with the oscillator frequency.



 $I_{DTC} \approx 13.3 \ [\mu A]$  $V_{DTC} \approx 0.99 \ [V]$  $Du \approx 52.3 \ [\%]$ 

There may be an operational delay of the PWM comparator and a difference in peak and trough values of the triangular wave oscillation. Discrepancies between the values obtained from the above formulas and the actual values may occur, in which case adjust the values on the mounting substrate.

In starting, if the capacitor  $C_{DTC}$  is added in parallel to the external resistor  $R_{DTC}$ , and the output pulse width are gradually widened, the AN8014S will be in soft-start operation. Thus the overshoot at the output of DC-DC converters can be prevented.

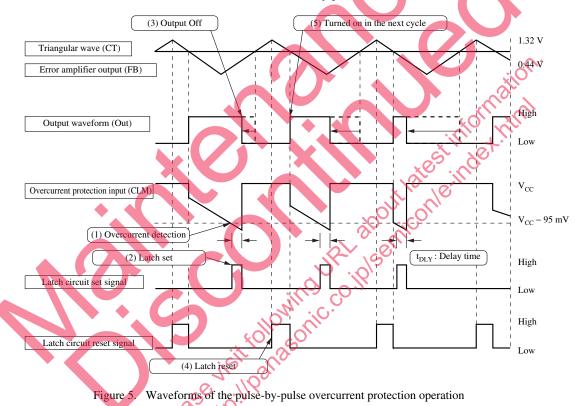
- [1] Function descriptions (continued)
- 8. Overcurrent protection block

Utilizing that the overcurrent of power output is proportional to the current value which flows in the main switch (power MOSFET), the block regulates the upper limit of the current flowing in the main switch, thus protects the parts such as main switch device, a flywheel diode and a choke coil from the damage caused by the overcurrent.

The current detection are done by monitoring, at CLM pin (pin 10), the voltage drop in resistor which is placed between the main switch device and  $V_{CC}$  pin.

When the main switch device (power MOSFET) is switched on and the voltage of CLM pin reaches " $V_{CC}$  – 95 mV", threshold level for overcurrent detection, the output drive transistor is cut off so that no more current flows in the main switch device. This control is repeated at each cycle. When overcurrent is detected once, the transistor remains off during the same cycle, and is switched on in the next cycle.

Such an overcurrent detection method is called "Pulse-by-pulse overcurrent detection."



R2 and C1 shown in figure 6 constitute a low-pass filter to eliminate noise due to parasitic capacitance when the power MOSFET is turned on.

The cut-off frequency of the filter is obtained from the following.

$$f_{\rm C} = \frac{1}{2\pi C_1 R_2} \quad [\rm Hz]$$

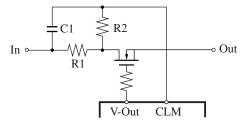
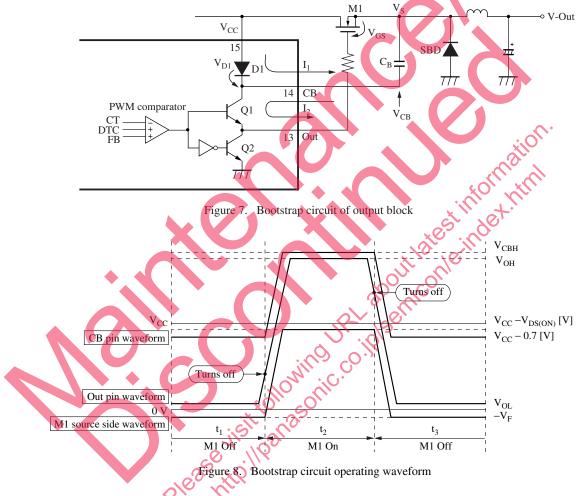


Figure 6. CLM noise filter circuit

- [1] Function descriptions (continued)
- 9. Bootstrap circuit of output block

If the n-channel MOSFET is used as a switching device for DC-DC converter control of step down method, a bootstrap circuit is required.

Bootstrap circuit ensures that the gate-source voltage is gate threshold voltage or higher by going up the high level of the Out pin (pin 13) than  $V_{CC}$  voltage when n-channel MOSFET turns on Figure 7 shows the output of bootstrap circuit including the external circuit. Figure 8 shows the operating waveform of the bootstrap circuit.



The following describes the operation of the bootstrap circuit.

1) N-channel MOSFET (M1) off time: t<sub>1</sub>

While the M1 is turned off, the choke coil is provided with energy from the Schottky barrier diode (SBD) and the source-side voltage  $V_S$  of the M1 is fixed to  $-V_F$ . The bootstrap capacitor  $C_B$  is charged from the  $V_{CC}$  pin (pin 15) through the AN8014S's internal diode D1.

The voltage  $V_{CB}$  on the CB pin (pin 14) is expressed by the following.

 $V_{S} = -V_{F}$  $V_{CB} = V_{CC} - V_{D1}$ 

 $V_F$ : Forward voltage of SBD

V<sub>D1</sub>: Forward voltage of D1

Therefore, the charged voltage of bootstrap capacitor C<sub>B</sub> is expressed by the following.

 $\mathbf{V}_{\mathrm{CB}} - \mathbf{V}_{\mathrm{S}} = \mathbf{V}_{\mathrm{CC}} - \mathbf{V}_{\mathrm{D1}} + \mathbf{V}_{\mathrm{F}}$ 

- [1] Function descriptions (continued)
- 9. Bootstrap circuit of output block (continued)
  - 2) N-channel MOSFET (M1) turn-on time: t<sub>2</sub>

When the PWM comparator output is inverted, the Out pin (pin 13) output changes into a high level. The Out pin voltage V<sub>O</sub> rises toward the CB pin voltage.

 $V_{O} = V_{CB} - V_{CE}(sat)$ 

Then the voltage between the gate and source of the M1 is obtained from the following.

 $V_{GS} = V_O + V_F$ 

When the Out pin voltage  $V_0$  is the same as or higher than the gate threshold voltage  $V_{TH}$ , the M1 turns on. Then the M1 source-side voltage rises up to the voltage expressed by the following.

 $V_{S} = V_{CC} - V_{DS(ON)}$ 

The bootstrap capacitor C<sub>B</sub> is connected to the source side and CB pin of the M1. Therefore, the CB pin voltage rises according to the M1 source-side voltage due to capacitor coupling. V<sub>CB</sub> is expressed by the following formula.

$$\begin{split} V_{CB} &= V_S + V_{CC} - V_{D1} + V_F \\ &= 2 \times V_{CC} - V_{D1} + V_{DS(ON)} + V_F \end{split}$$

3) N-channel MOSFET (M1) turn-off time: t<sub>3</sub>

The Out pin voltage turns off after rising to the saturation voltage of the AN8014S's internal transistor Q1. The M1 source-side voltage drops to  $-V_F$ . The CB pin voltage drops to  $V_{CC} - V_{D1}$  or below due to capacitive coupling. Then the M1 will be in the state described in the above 1).

#### [2] Bootstrap circuit usage notes

1. Operating voltage range for step-down circuit

Just like what described previously, if a step-down circuit is in DC-DC converter control, the CB pin (pin 14) voltage will be approximately twice as high as V<sub>CC</sub> when the n-channel MOSFET as a switching element is turned on. The allowable voltage applied to the CB pin is 35 V. Therefore the operating supply voltage must be within a range between 3.6 V and 17 V.

 $V_{CB} = 2 \times V_{CC} - V_{D1} - V_{DS(ON)} + V_F < 35[V]$ 

$$\frac{35 + V_{D1} + V_{DS(ON)} - V_F}{V_F}$$
 [V] < 17 [V]

Value setting of bootstrap capacitor

The bootstrap capacitor raises the CB pin voltage to V<sub>CC</sub> or higher due to capacitor coupling to the source side of the n-channel MOSFET when the n-channel MOSFET is turned on. At that time bootstrap capacitor is discharged by n-channel MOSFET gate-drive-current. If the capacitance of the bootstrap capacitor is too low, an increase in switching loss will result, which will reduce the efficiency.

Therefore, the capacitance must be large enough in comparison with the gate input capacitance of the nchannel MOSFET. Refer to the following.

 $C_B > C_{iss}$ 

Determine the best value by testing on the printed circuit board for mounting.

3. CB pin connection for step-up circuit

If a step-up circuit is in DC-DC converter control, no bootstrap circuit is required because the source side of the n-channel MOSFET is grounded. Therefore, short-circuit the CB pin (pin 14) and the  $V_{CC}$  pin (pin 15).

Thus, the operating supply voltage range in the step-up circuit method is between 3.6 V and 34 V.

[3] Timing chart

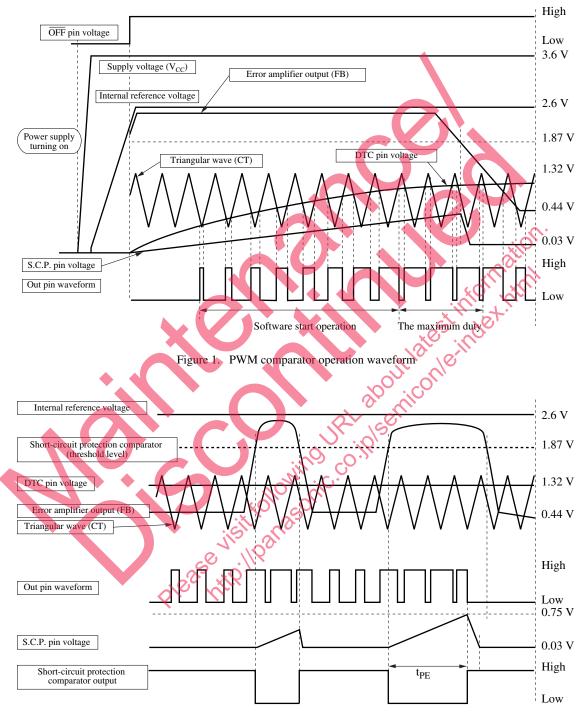
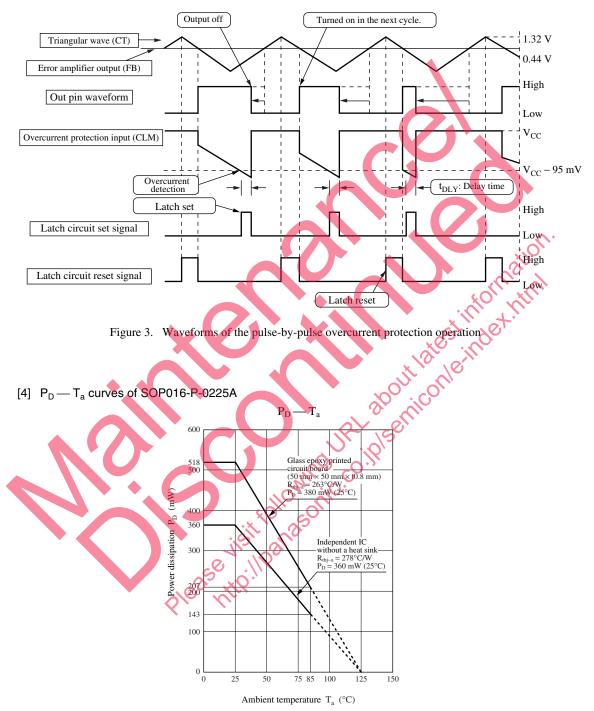


Figure 2. Short-circuit protection operation waveform

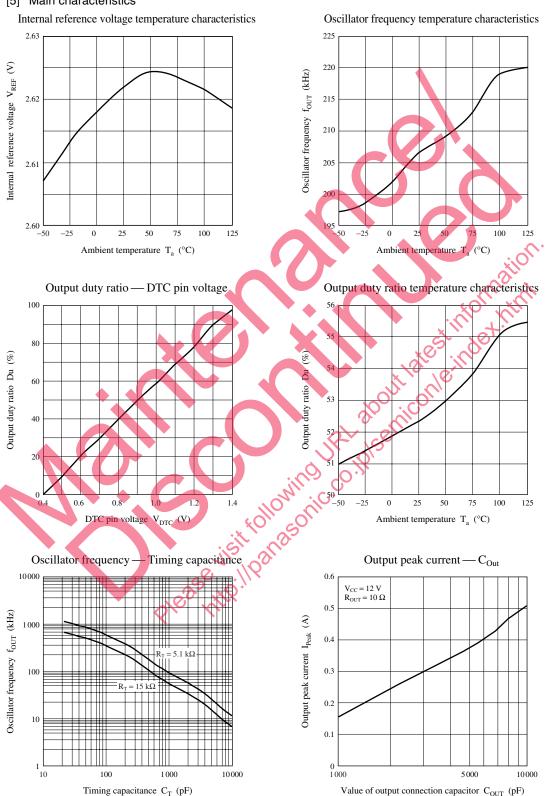
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#### Application Notes (continued)

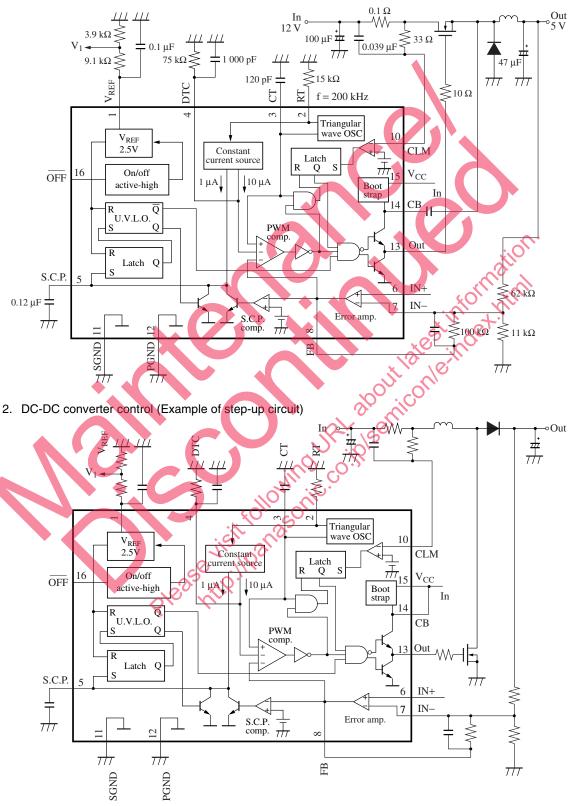
[3] Timing chart (continued)



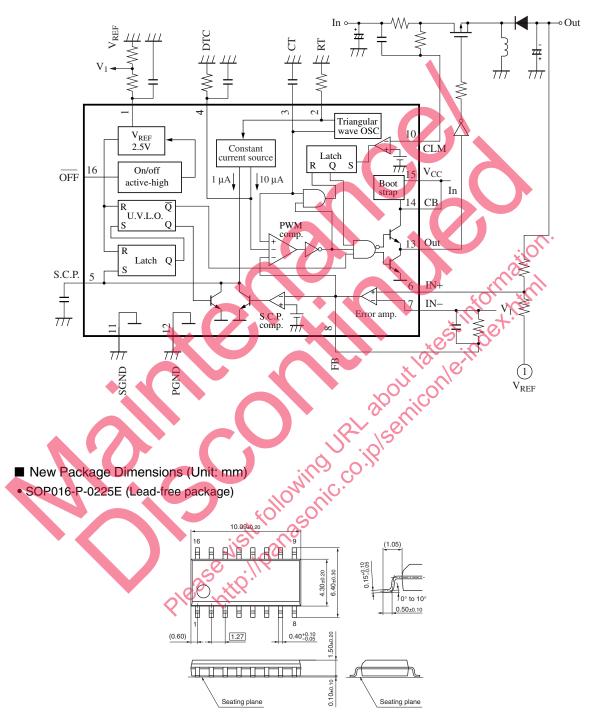




- Application Circuit Examples
- 1. DC-DC converter control (Example of step-down circuit)



- Application Circuit Examples (continued)
- 3. DC-DC converter control (Example of polarity-inverting circuit)



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